Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC 1752 Standard Form Type				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information			
Supplie	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2025-06-06			
Contact N	lame	Title - Contact]	Phone - Contact*					Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing Site			ng Site	W	Veight*	UOM	Unit Type	
		EGP30G	EGP30G HER DO201AD		PPN 3A 400V		2025-06-06	5 TSCE		ГЅСВЕ		40	0.00	mg	Each
Manufa	cturing Proccess Informa	ition							,						
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-02		STD-020 MSL	Rating	Peak Process Body Temperature		re Max Tir	ne at Peak	Temperatu	re Numb	per of Reflow Cyc	eles	
	Matte Tin (Sn) - annealed		CU Alloy NA		A		0		С	30		second	ls 3		
Comments	3														
				_	_										_
or more	information regarding materia	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier need is supplier has not or										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.464	mg	Supplier	Silicon (Si)	7440-21-3		1.3176	mg
			В	Nickel (Ni)	7440-02-0		0.0095	mg
			Supplier	Gold (Au)	7440-57-5		0.0022	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.1347	mg
Die Attach	3.36	mg	Supplier	Silver (Ag)	7440-22-4		0.1848	mg
			A	Lead (Pb)	7439-92-1	7a	3.0912	mg
			Supplier	Tin (Sn)	7440-31-5		0.084	mg
Lead Wire	303.216	mg	Supplier	Copper (Cu)	7440-50-8		303.216	mg
Marking Ink	0.2	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.01	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.01	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.02	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.13	mg
			Supplier	Aluminum (Al)	7429-90-5		0.03	mg
Mold Compound-Black	83.56	mg		Metal Hydroxide	proprietary data		3.9273	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2507	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		66.848	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		8.356	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.178	mg
Plating	8.2	mg	Supplier	Tin (Sn)	7440-31-5		8.2	mg